



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



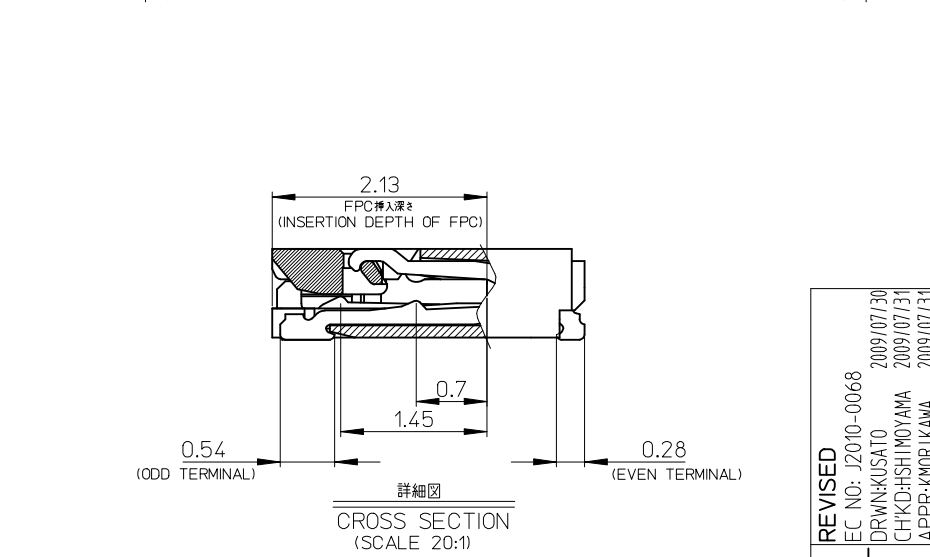
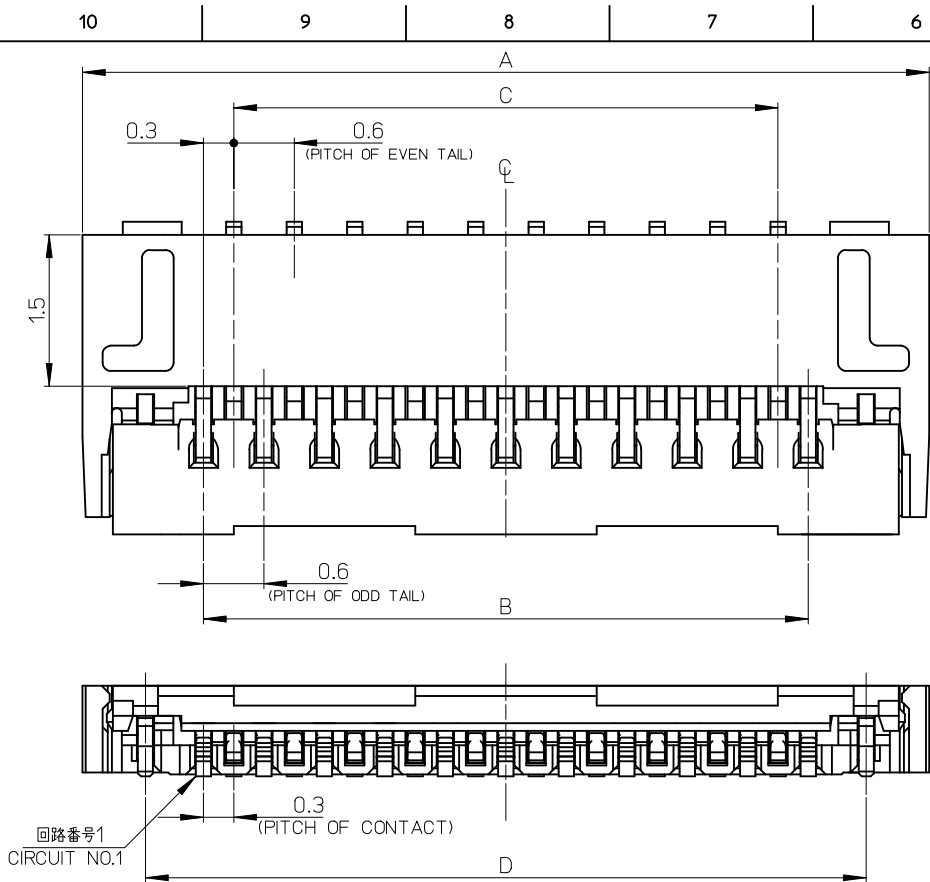
Contact us

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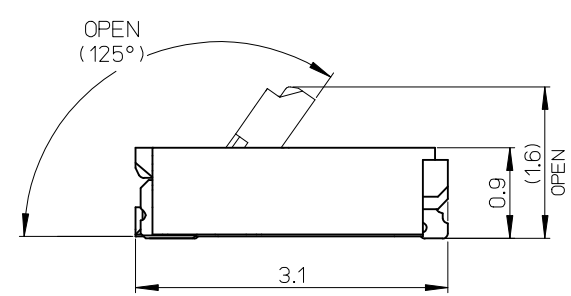
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





注記
NOTES:
1.材質
MATERIAL
ハウジング:LCP(液晶ポリマー)、ガラス充填、UL94V-0
HOUSING:LCP(LIQUID CRYSTAL POLYMER),
GLASS FILLED,UL94V-0
アクチュエータ:ナイロン、ガラス充填、UL94V-0
ACTUATOR:NYLON(POLYAMIDE),
GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.15)
TERMINAL:COPPER ALLOY(t=0.15)
金具:銅合金(t=0.15)
NAIL:COPPER ALLOY(t=0.15)

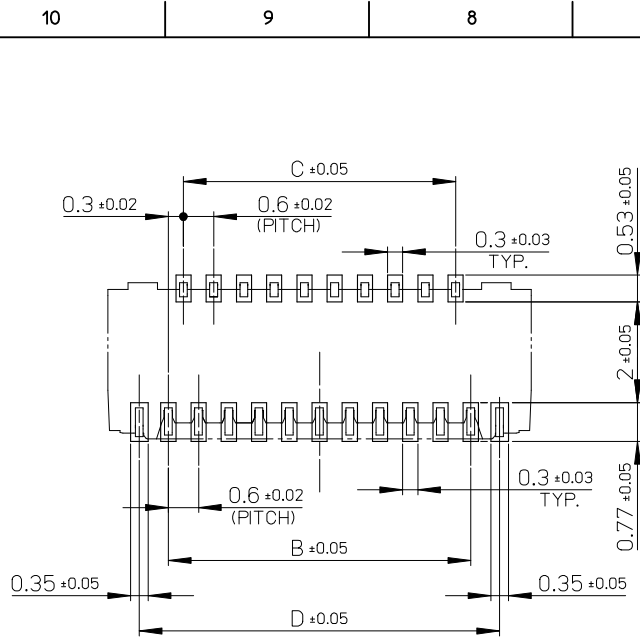
2.めっき仕様
PLATING
ターミナル
TERMINAL
部分金めっき
SEPARATED GOLD PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
金具
NAIL
銅めっき
TIN PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



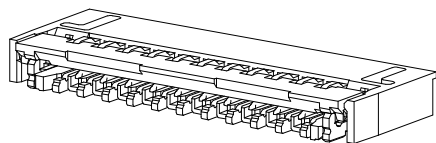
| | | | | | | |
|---------------------|-------|------|------|------|--------------------------------------|----------------|
| 0.10 | 16.15 | 14.4 | 15 | 17.4 | 501628-5191 | 51 |
| 0.089 | 14.35 | 12.6 | 13.2 | 15.6 | 501628-4591 | 45 |
| 0.078 | 12.55 | 10.8 | 11.4 | 13.8 | 501628-3991 | 39 |
| 0.075 | 11.95 | 10.2 | 10.8 | 13.2 | 501628-3791 | 37 |
| 0.071 | 11.35 | 9.6 | 10.2 | 12.6 | 501628-3591 | 35 |
| 0.067 | 10.75 | 9.0 | 9.6 | 12.0 | 501628-3391 | 33 |
| 0.064 | 10.15 | 8.4 | 9 | 11.4 | 501628-3191 | 31 |
| 0.056 | 8.95 | 7.2 | 7.8 | 10.2 | 501628-2791 | 27 |
| 0.046 | 7.15 | 5.4 | 6 | 8.4 | 501628-2191 | 21 |
| 0.028 | 4.15 | 2.4 | 3 | 5.4 | 501628-1191 | 11 |
| 重さ (g) WEIGHT(g) | D | C | B | A | EMBOSSED PACKAGE オーダー番号 ORDER No. | 極数 CIRCUITS |

CONNECTOR SERIES No. 501628-**11

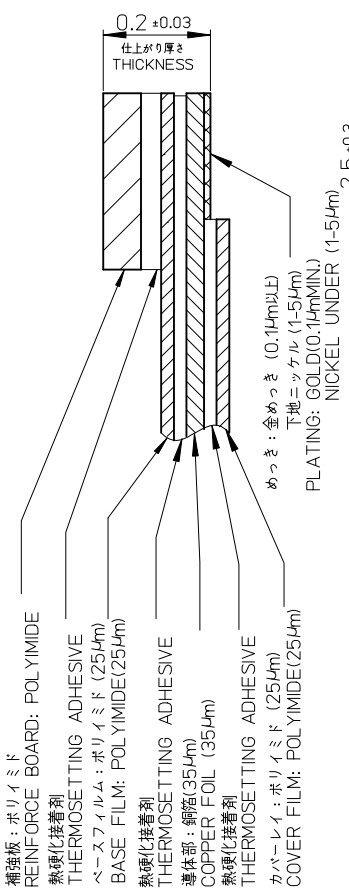
| | | | | | | |
|---|---------------------------------------|--|----------------------------|---|--|-------------------------------|
| REVISED EC NO: J2010-0068 DRWN:KUSATO 2009/07/30 CHKD:HSHIMOYAMA 2009/07/31 APPR:KMORIKAWA 2009/07/31 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE 40:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ±0.2 | DRAWN BY HSHIMOYAMA | DATE 2005/03/25 | TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY HHIRATA | DATE 2005/03/25 | MOLEX INCORPORATED | |
| | 30 OVER | ±0.3 | APPROVED BY MSASAO | DATE 2005/03/25 | MATERIAL NO. SEE TABLE | DOCUMENT NO. SD-501628-001 |
| | ANGULAR ±1° | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | SIZE A3 | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |



推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)

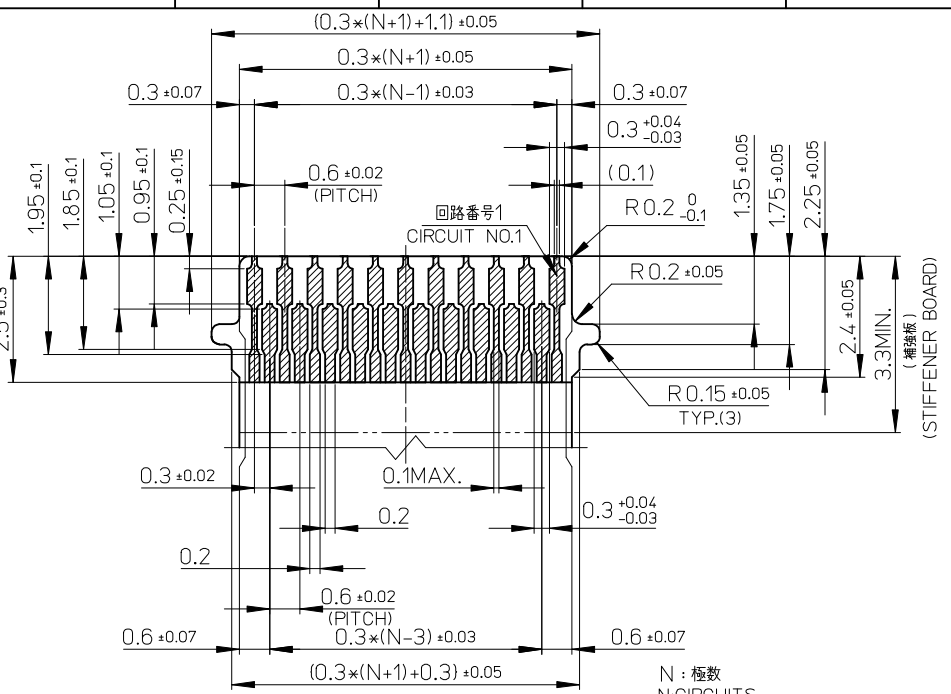


ISO VIEW (参考)



補強板: ポリイミド
REINFORCE BOARD: POL YIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25 μ m)
BASE FILM: POLYIMIDE(25 μ m)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35 μ m)
CONDUCTOR: COPPER FOIL (35 μ m)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25 μ m)
COVER FILM: POLYIMIDE(25 μ m)

FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

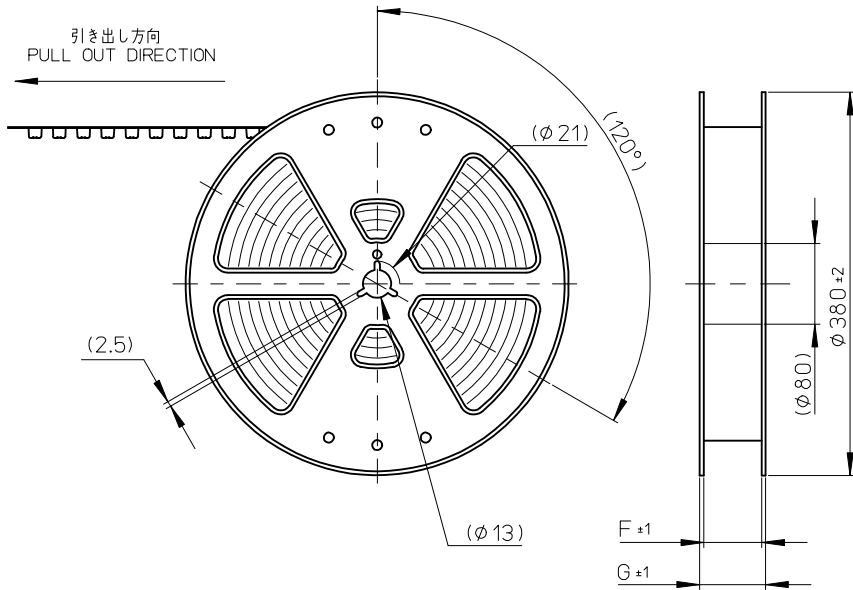
FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

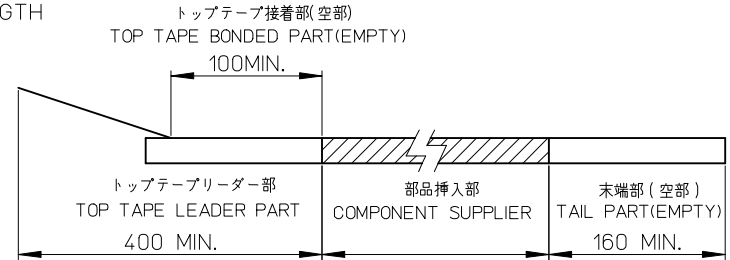
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|--|---------------------------------------|--|----------------------------|---|--|-------------------------------|------------------------|
| REVISED EC NO: J2010-0068 DRWN: KUSATO 2009/07/30 CHKD: HSHIMOYAMA 2009/07/31 APPR: KMORIKAWA 2009/07/31 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 40:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ± 0.2 | DRAWN BY HSHIMOYAMA | DATE 2005/03/25 | TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER | | |
| | 10 OVER 30 UNDER | ± 0.25 | CHECKED BY HHIRATA | DATE 2005/03/25 | MOLEX INCORPORATED | | |
| | 30 OVER | ± 0.3 | APPROVED BY MSASAO | DATE 2005/03/25 | MATERIAL NO. SEE TABLE | DOCUMENT NO. SD-501628-001 | SHEET NO. 2 OF 2 |
| REVISIONS | ANGULAR ± 1 ° | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | |

注記)
NOTES

- 製品番号501628-***11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 501628-***11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH

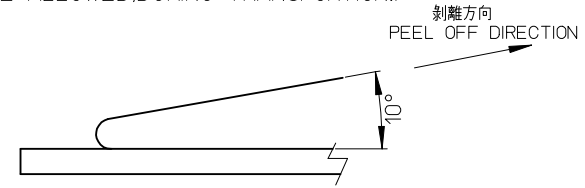


引き出し方向
PULL OUT DIRECTION



- トップテープの剥離強度 (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
0.1-1.3N (10-130gf)
尚、本規格値は出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しないこと)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.)

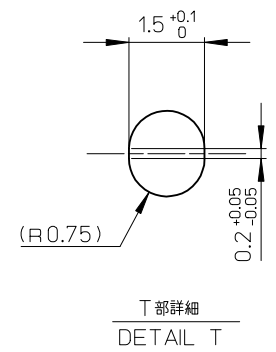
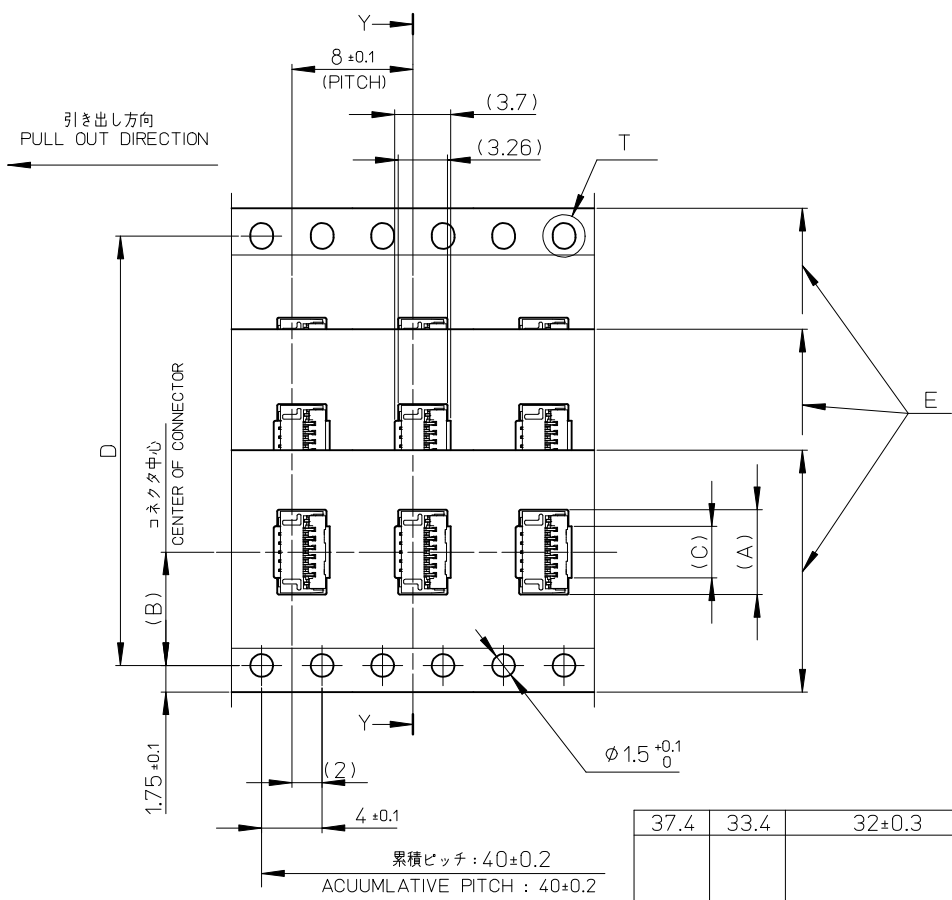
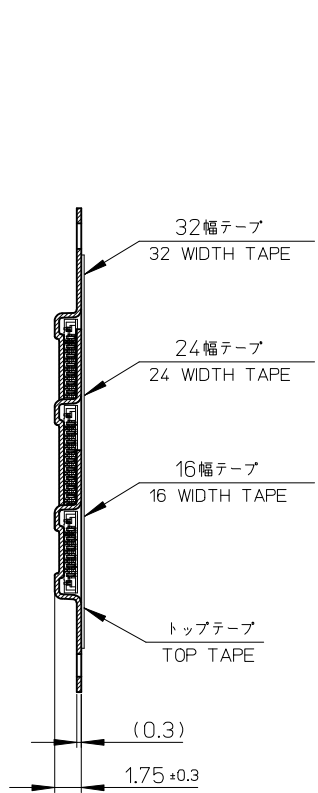
引き出し方向
PULL OUT DIRECTION



- 材料
MATERIAL
キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: PET、PE、PEF
TOP TAPE : PET, PE, PEF
リール: ポリスチレン
REEL: POLYSTYLENE

- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

| | | | | | | | | | | |
|--|--------------------|--|-------|----------------------------|--------------------|---|------------------------|------------------------|--|--|
| REVISED EC NO: J2010-0068 DRW: KUSATO 2009/07/30 CHKD: HSHIMUYAMA 2009/07/31 APP: KMORIKAWA 2009/07/31 | DESCRIPTION REV | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | 10 UNDER | ± --- | DRAWN BY HSHIMUYAMA | DATE 2005/08/22 | TITLE 0.3 FPC CONN.(FOR 501628 -***11) TAPING PACKAGE NICKEL BARRIER | | | | |
| | | 10 OVER 30 UNDER | ± --- | CHECKED BY HIRATA | DATE 2005/08/22 | MOLEX INCORPORATED | | | | |
| | | 30 OVER | ± --- | APPROVED BY MSASAO | DATE 2005/08/22 | DOCUMENT NO. SD-501628-003 | | | | |
| ANGULAR ± --- ° | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. SEE TABLE | | SHEET NO. 1 OF 2 | | | | |
| | | | | SIZE A3 | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |



| | | | | | | | | | |
|------|------|-----------------------------------|------|------|------|------|-------------|----------------------|----------------|
| 37.4 | 33.4 | 32 ± 0.3 | 28.4 | 15.4 | 14.2 | 17.6 | 501628-5191 | 51 | |
| 29.4 | 25.4 | 24 ± 0.3 | --- | 13.6 | 11.5 | 15.8 | 501628-4591 | 45 | |
| | | | | 11.8 | | 14 | 501628-3991 | 39 | |
| | | | | 11.2 | | 13.4 | 501628-3791 | 37 | |
| | | | | 10.6 | | 12.8 | 501628-3591 | 35 | |
| | | | | 10.0 | | 12.2 | 501628-3391 | 33 | |
| | | | | 9.4 | | 11.6 | 501628-3191 | 31 | |
| 21.4 | 17.4 | 16 ± 0.3 | --- | 8.2 | 7.5 | 10.4 | 501628-2791 | 27 | |
| | | | | 6.4 | | 8.6 | 501628-2191 | 21 | |
| | | | | 3.4 | | 5.6 | 501628-1191 | 11 | |
| G | F | E キャリアテープ幅 EMBOSSED TAPE WIDTH | | D | C | B | A | 製品番号 MATERIAL NO. | 極数 CIRCUITS |

| | | | | | | | | | | |
|---|--------------------|--|-------|---|--------------------|--|------------------------|-------------------------------|------------------------|--|
| REVISED EC NO: J2010-0068 DRW: KUSATO 2009/07/30 CHK: HSHIMUYAMA 2009/07/31 APP: KMORIKAWA 2009/07/31 | DESCRIPTION REV | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | | THIRD ANGLE PROJECTION | |
| | | 10 UNDER | ± --- | DRAWN BY HSHIMUYAMA | DATE 2005/08/22 | TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER | | | | |
| | | 10 OVER 30 UNDER | ± --- | CHECKED BY HHRATA | DATE 2005/08/22 | MOLEX INCORPORATED | | | | |
| | | 30 OVER | ± --- | APPROVED BY MSASAO | DATE 2005/08/22 | MATERIAL NO. SEE TABLE | | DOCUMENT NO. SD-501628-003 | SHEET NO. 2 OF 2 | |
| ANGULAR ± --- ° | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | |